IN THE SPECIFICATION

Please replace the paragraph beginning on page 2, line 4 with the following paragraph:

Separate processor subsystems have necessitated an increased focus by circuit designers on high-speed processor to processor communications. Recently, particular attention has been paid to providing a high-speed, reliable standard for a communications interface between an embedded general purpose applications processor and a baseband processor. One example of a high-speed processor to processor communications interface is Intel® Corporation's ~~Multiple~~ Mobile Scalable Link® (MSL) technology. Factors considered for an inter-processor communications standard may include high inter-processor data transmission rates, scalability for increasing bandwidth, QoS, security, and the elimination of data exchange bottlenecks. Unlike the typical personal computer, however, these devices have to be designed with severe packaging and power consumption constraints in mind.

Please replace the paragraph beginning on page 4, line 15 with the following paragraph:

In one embodiment, the multi-point, inter-device communications link 110 may be a data link between a plurality of applications and/or communications subsystems. For example, the link 110 may be a dedicated and optimized high speed interface that allows for multi-point data transmissions between a plurality of embedded applications processor devices. One inter-device communications link 110 that may be suitable for performing the functions described herein is the Intel® Corporation's ~~Multiple~~Mobile Scalable Link® (MSL) technology, however, this link is not limited to such inter-device communications link. As such, other inter-device communications links capable of, for example, one hundred megabit/second or greater data rates and for providing a common, multi-point interface for communicating between embedded applications processors, may be suitable for performing the functions herein.